

650V N-Channel MOSFET

FEATURES

- Fast switching
- 100% avalanche tested
- Improved dv/dt capability

APPLICATIONS

- Switch Mode Power Supply (SMPS)
- Uninterruptible Power Supply (UPS)
- Power Factor Correction (PFC)

Device Marking and Package Information			
Device	Package	Marking	
TMA7N65H	TO-220F	A7N65H	
TMP7N65H	TO-220	P7N65H	
TMD7N65H	TO-252	D7N65H	
TMU7N65H	TO-251	U7N65H	

TO-220F 605	TO-251 GDS	TO-252 G ^D S
rmation arking 7N65H	TO-220 GDS	Go

Absolute Maximum Ratings	solute Maximum Ratings $T_c = 25^{\circ}C$, unless otherwise noted						
Deremeter		Symbol	Value			Unit	
Parameter		Symbol	TO-220F	TO-251	TO-252	TO-220	Unit
Drain-Source Voltage (V_{GS} = 0V)		V _{DSS}		65	50		V
Continuous Drain Current		I _D		7	7		А
Pulsed Drain Current	(note1)	I _{DM}		2	8		А
Gate-Source Voltage		V _{GSS}		±	30		V
Single Pulse Avalanche Energy	(note2)	E _{AS}		19	98		mJ
Avalanche Current	(note1)	I _{AR}		3.	.5		А
Repetitive Avalanche Energy	(note1)	E _{AR}		4	0		mJ
Power Dissipation (T _C = 25°C)		P _D	63		97		W
Operating Junction and Storage Tempo	erature Range	T _J , T _{stg}		-55~-	+150		°C

Thermal Resistance						
Parameter	Symbol		Val	ue		Unit
Parameter	Symbol	TO-220F	TO-251	TO-252	TO-220	
Thermal Resistance, Junction-to-Case	R_{thJC}	1.98		1.29		°C/W
Thermal Resistance, Junction-to-Ambient	R _{thJA}	62.5		60		C/W



Specifications T _J = 25°C, ur	less othe	rwise noted				
Devenueter	Cumhal	Test Conditions		Value		11
Parameter	Symbol	Test Conditions	Min.	Тур.	Max.	Unit
Static						
Drain-Source Breakdown Voltage	V _{(BR)DSS}	V_{GS} = 0V, I _D = 250µA	650			V
Zero Gate Voltage Drain Current	I _{DSS}	V_{DS} = 650V, V_{GS} = 0V, T_{J} = 25°C			1	μA
Gate-Source Leakage	I _{GSS}	V_{GS} = $\pm 30V$			±100	nA
Gate-Source Threshold Voltage	V _{GS(th)}	$V_{DS} = V_{GS}, I_D = 250 \mu A$	3.0		4.0	V
Drain-Source On-Resistance (Note3)	R _{DS(on)}	V _{GS} = 10V, I _D = 3.5A		1.1	1.35	Ω
Dynamic						
Input Capacitance	C _{iss}	V _{GS} = 0V,		891		
Output Capacitance	C _{oss}	V _{DS} = 25V,		110		pF
Reverse Transfer Capacitance	C _{rss}	f = 1.0MHz		14		
Total Gate Charge	Q _g			22		
Gate-Source Charge	Q_gs	V _{DD} = 520V, I _D = 7A, V _{GS} = 10V		4.3		nC
Gate-Drain Charge	Q_{gd}			13		
Turn-on Delay Time	t _{d(on)}			15		
Turn-on Rise Time	t _r	V _{DD} = 325V, I _D = 7A,		18		
Turn-off Delay Time	$t_{d(off)}$	$R_{G} = 25 \Omega$		80		ns
Turn-off Fall Time	t _f			35		
Drain-Source Body Diode Character	istics			-		
Continuous Body Diode Current	I _S	T 05 00			7.0	۸
Pulsed Diode Forward Current	I _{SM}	T _C = 25 °C			28	A
Body Diode Voltage	V_{SD}	T_{J} = 25°C, I_{SD} = 7A, V_{GS} = 0V			1.4	V
Reverse Recovery Time	t _{rr}	V _{GS} = 0V,I _S = 7A,		300		ns
Reverse Recovery Charge	Q _{rr}	di _F /dt =100A /µs		4.1		μC

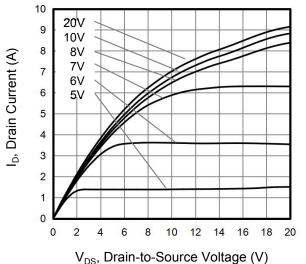
Notes

- 1. Repetitive Rating: Pulse width limited by maximum junction temperature
- 2. I_{AS} = 4.5A, V_{DD} = 50V, R_{G} = 25 Ω , Starting T_{J} = 25 °C
- 3. Pulse Test: Pulse width \leq 300µs, Duty Cycle \leq 1%



Typical Characteristics $T_J = 25^{\circ}C$, unless otherwise noted







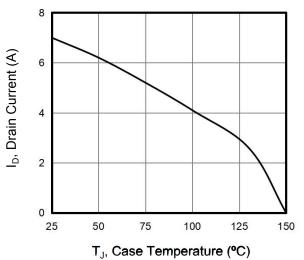
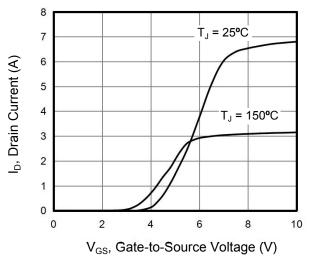


Figure 5. Transfer Characteristics



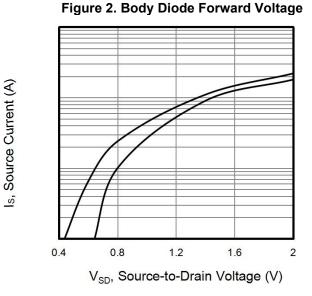


Figure 4. BV_{DSS} Variation vs. Temperature

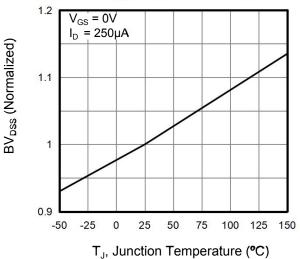
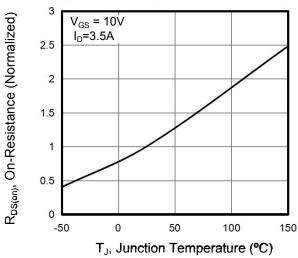


Figure 6. On-Resistance vs. Temperature



V3.0

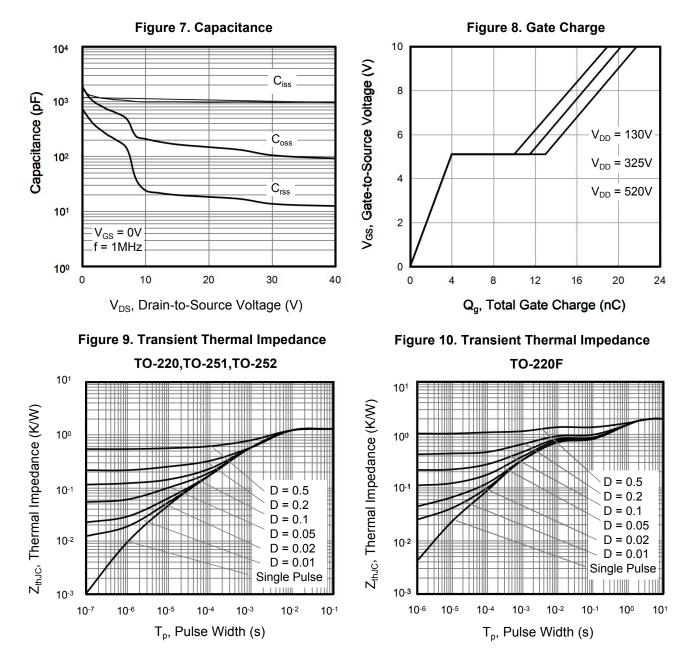
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TMA7N65H, TMP7N65H, TMD7N65H, TMU7N65H

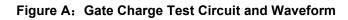


Wuxi Unigroup Microelectronics Company

Typical Characteristics $T_J = 25^{\circ}C$, unless otherwise noted







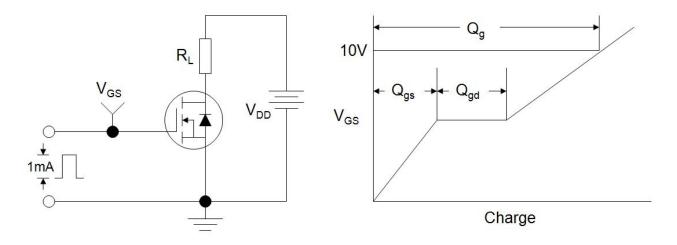


Figure B: Resistive Switching Test Circuit and Waveform

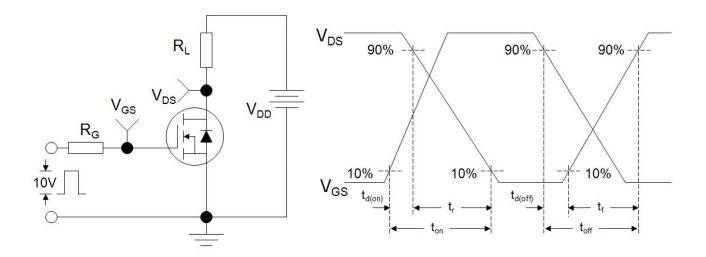
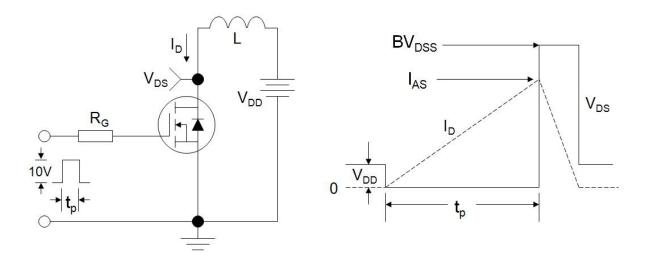
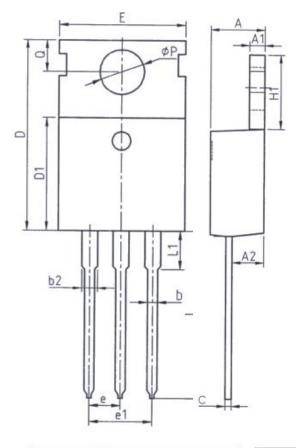


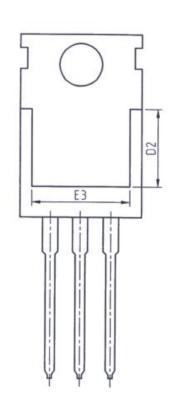
Figure C: Unclamped Inductive Switching Test Circuit and Waveform





TO-220

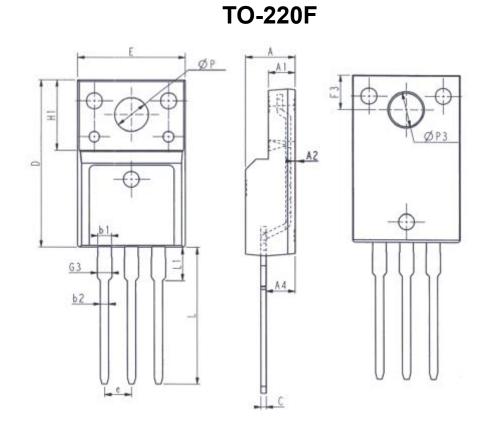




Unit: mm			
Symbol	Min.	Max.	
A	4.37	4.77	
A1	1.25	1.45	
A2	2.20	2.60	
b	0.70	0.95	
b2	1.17	1.47	
С	0.40	0.65	
D	15.10	16.10	
D1	8.80	9.40	
D2	5.50	-	

	Unit: mm	
Symbol	Min.	Max.
E	9.70	10.30
E3	7.00	
e	2.54	4BSC
e1	5.08	BBSC
H1	6.25	6.85
L	12.75	13.80
L1	1	3.40
P	3.40	3.80
Q	2.60	3.00

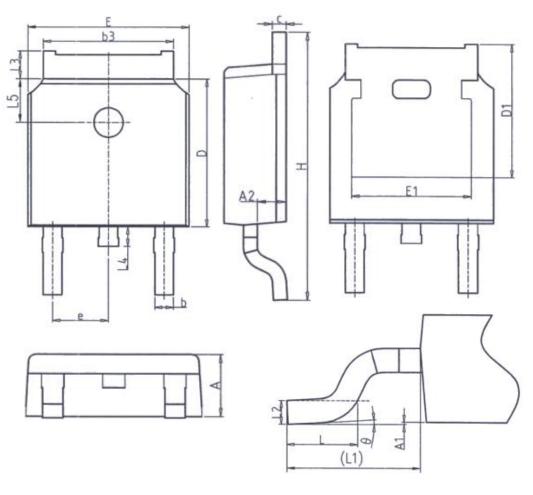




Unit: mm		l	Unit: mr	n	
Symbol	Min.	Max.	Symbol	Min.	Max.
E	9.96	10.36	L	12.68	13.28
A	4.50	4.90	L1	2.93	3.13
A1	2.34	2.74	P	3.03	3.38
A2	0.30	0.60	P3	3.15	3.65
A4	2.56	2.96	F3	3.15	3.45
С	0.40	0.65	G3	1.25	1.55
D	15.57	16.17	b1	1.18	1.43
H1	6.70	OREF	b2	0.70	0.95
e	2.54	4BSC			



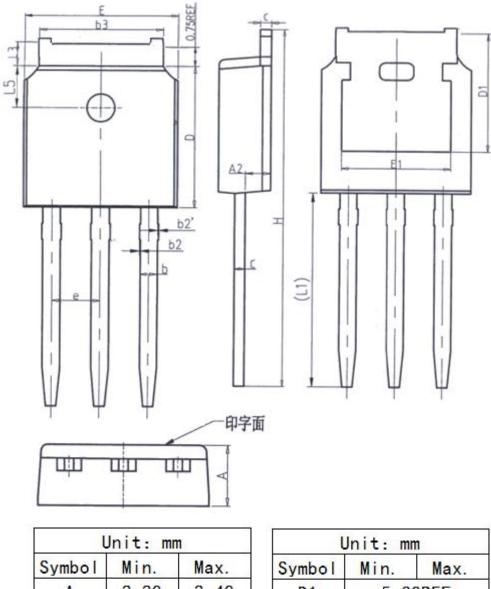
TO-252



	-	-
Symbol	Min.	Max.
Α	2.20	2.40
A1	0.00	0.20
A2	0.97	1.17
b	0.68	0.90
b3	5.20	5.50
С	0.43	0.63
D	5.98	6. 22
D1	5.30	OREF
E	6.40	6.80
E1	4.63	

Symbol	Min.	Max.
e	2. 28	6BSC
Н	9.40	10. 50
L	1.38	1.75
L1	2.9	OREF
L2	0.5	1BSC
L3	0.88	1.28
L4	177	1.00
L5	1.65	1.95
θ	0°	8°





TO-251

L	Jnit: mr	n
Symbol	Min.	Max.
Α	2.20	2.40
A2	0.97	1.17
b	0.68	0.90
b2	0.00	0.10
b2'	0.00	0.10
b3	5.20	5.50
С	0.43	0.63
D	5.98	6.22

Symbol	Min.	Max.	
D1	5.30	DREF	
E	6.40	6.80	
E1	4.63	-	
e	2. 286BSC		
H	16.22	16.82	
L1	9.15	9.65	
L3	0.88	1.28	
L5	1.65	1.95	



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